

Easy-Mix HT 180 Epoxy Adhesive



high-temperature resistant steady shock and impact resistant

WEICON Easy-Mix HT 180 is a 2-component adhesive on epoxy resin basis and has a high temperature resistance of up to +180°C; short term to +230°C.

The adhesive is highly viscous and stable which makes it also suitable for vertical applications. It is shock and impact resistant, has a long pot life, cures at room temperature, can be processed mechanically and his special fillers allow a constant bonding line. The adhesive is particularly suitable for the bonding of composite materials and metal and can be spot-welded while curing.

Easy-Mix HT 180 can furthermore be utilised for plastics, ceramic, glass, stone or wood and is suitable for adhesions where larger tolerances have to be bridged. Due to special fillers it is possible to achieve a constant and reliable bonding line of at least 0.20 -0.25 mm.

The high temperature resistance permits the bonding of components which require powder-coating after complete curing.

Technical Data

Base	Epoxy resin mineral-filled
Texture	paste consistency, crack-filler
Colour	black
Mixing ratio by weight (Resin / Hardener)	2:1
Density of the mixture	1,1 g/cm ³
Viscosity of the mixture at 20°C (+68°F)	pasty
Adhesive gap bridging up to max.	4 mm
Processing temperature	+10 to +40 °C
Curing temperature	+10 to +50 °C
Pot life at 20°C (+68°F) for 10ml material	60 min.
Handling strength (35% strength) after	120 min.
Capable of bearing mechanical loads (50% strength) after	er 4 h

Final strength (100%) after	24 h
Medium strength of the pure epoxy resin accord	ing to DIN EN 1465
Pressure	52 Mpa
Pull	27 Mpa
Bending	46 Mpa
Tg after curing at room temperature	54,4 °C
Tg after tempering (at 120 °C)	44,7 °C
E-Modul	2.300 - 2.700 Mpa
Shore hardness D	80
Medium shear strength according to DIN EN 146	65 at
Galvanized steel	8 N/mm²
Steel sand blasted	23 N/mm²
Alu sandblasted	13 N/mm²
V2A polished	24 N/mm²
PVC hard-roughened	11 N/mm²
CFK	22 N/mm²
Linear shrinkage	0,3 %
Temperature resistance	-50 to 180 briefly to +230 °C
Thermal diffusivity (23 °C)	0,172 mm²/s
Thermal conductivity	0,26 W/m·K
Specific heat capacity	1,335 J/(g·K)
Resistivity	2,48 · 10^11 Ωm

Surface pre-treatment

To ensure a perfect bond, the surfaces to be joined must be clean and dry (e.g., clean and degrease using WEICON Surface Cleaner).

WEICON Easy-Mix products can be processed directly from the double cartridges with the help of the included static mixer. Reject the first 5 cm of the dosed bead. Apply adhesive to only one of the surfaces to be bonded. The pot life given is for a material quantity of 10 ml at room temperature. If larger quantities are used, the curing time will be faster. Similarly, higher ambient temperatures shorten the cure times (as a rule of thumb, every +10°C increase above room temperature will halve working and curing time). Temperatures below +16°C will extend working and curing times considerably, while below about +5°C, no reaction will take place at all.

Storage

When unopened and stored at a constant room temperature of approx. +20°C in a dry place, WEICON HT 180 has a shelf life of at least 24 months. Protect from direct sunlight. In case of non-observance of these storage instructions, the shelf life is reduced to 6 six months. In general, epoxy resins tend to crystallise at temperatures below +5°C. This effect is increased by large temperature fluctuations, e.g. during transport especially in the winter months. This has a negative impact on processing, curing

The specifications and recommendations given in this technical data sheet must not be seen as guaranteed product characteristics. They are based on our laboratory tests and on practical experience. Since individual application conditions are beyond our knowledge, control and responsibility, this information is provided without any obligation. We do guarantee the continuously high quality of our products. However, own adequate laboratory and practical tests to find out if the product in question meets the requested properties are recommended. A claim cannot be derived from them. The user bears the only responsibility for non-appropriate or other than specified applications.

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Technical Datasheet

and technical data, can, however, be reversed by heating the product (up to max. +50°C, no open flame). In WEICON Epoxy Adhesives, crystallisation is reduced by the careful choice and combinations of base resins (bisphenol A and F).

Safety and health

When using WEICON products, the physical, safety technical, toxicological and ecological data and regulations in our EC safety data sheets (www.weicon.com) must be observed.

Available sizes:

10650850 Easy-Mix HT 180 Epoxy Adhesive 50 ml

Accessories:

10650006 Mixing Nozzles, 10653050 Dispenser D 50, 50 ml

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